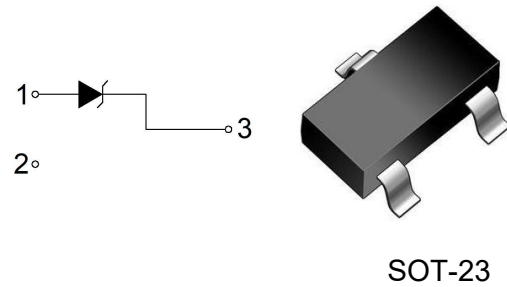


Plastic-Encapsulate Zener Diode

Parameter	Value	Unit
V_Z	2.4~75	V
P_D	300	mW



Features

- Low profile package
- Ideal for automated placement
- Low Zener Impedance
- Power Dissipation of 300mW
- High Stability and High Reliability

Applications

- Surge protection
- Voltage stabilization
- Polarity Protection

Absolute Maximum Ratings (T_A=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Forward Voltage (Note 1) @ I _F = 10mA	V _F	0.9	V
Power Dissipation(Note 2)	P _D	300	mW
Thermal Resistance from Junction to Ambient	R _{θJA}	417	°C/W
Junction Temperature	T _J	-55~+150	°C
Storage Temperature Range	T _{STG}	-55~+150	°C

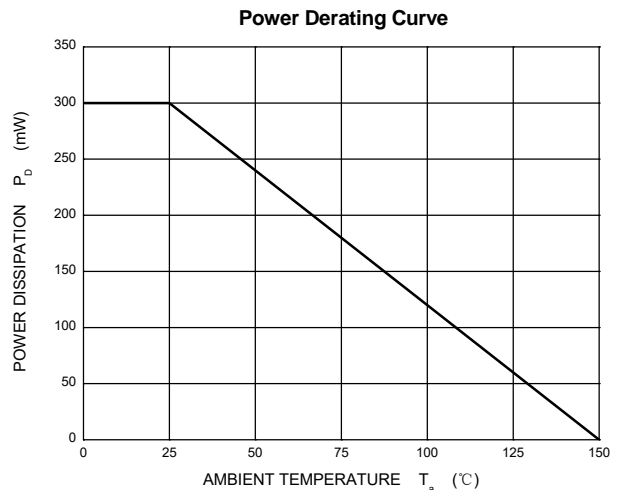
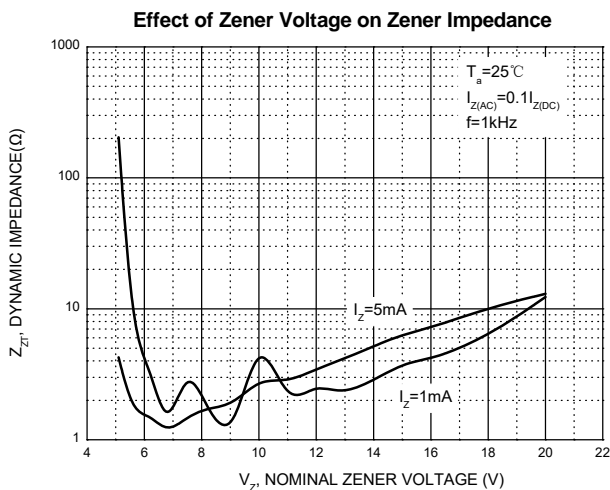
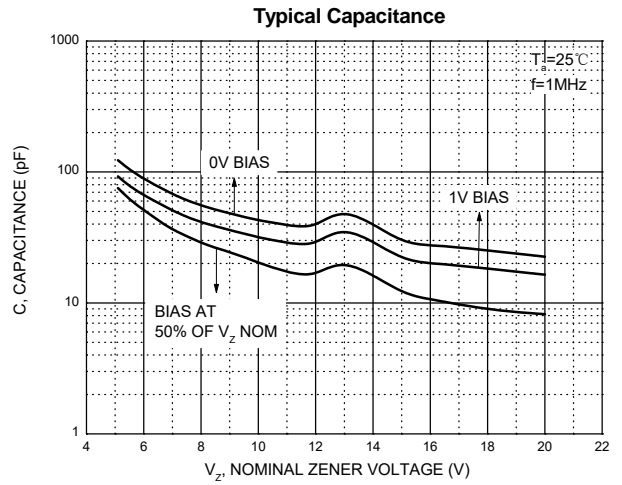
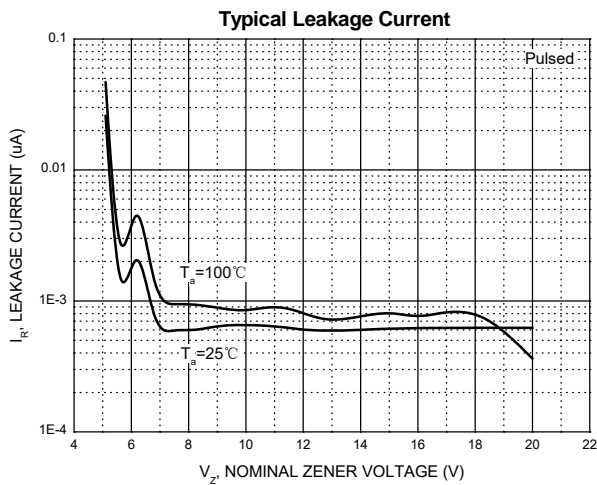
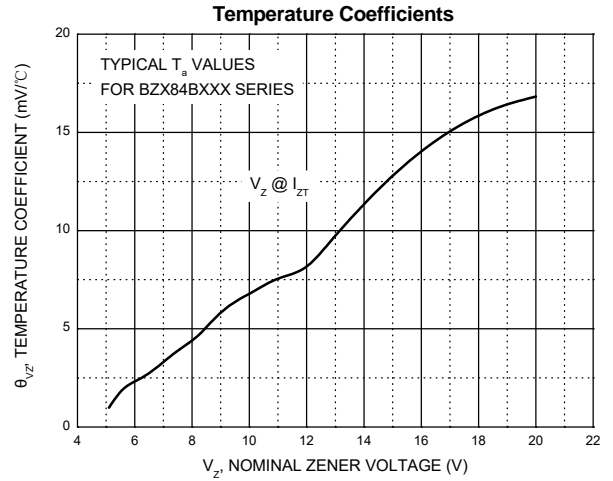
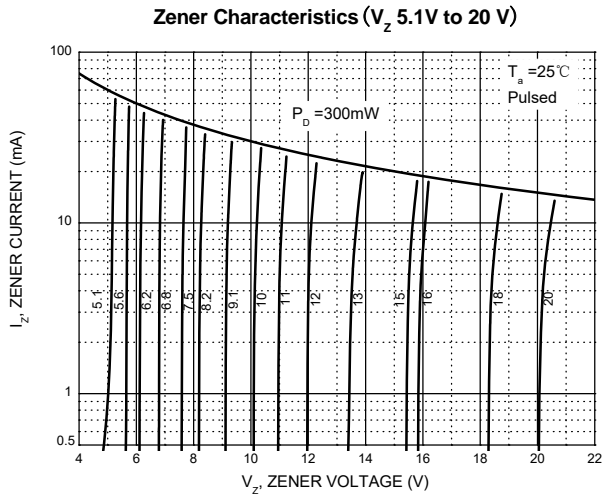
Electrical Characteristics (T_A=25°C)

Part Number	Marking	Nominal Zener Voltage @IZT①				Maximum Zener impedance ③			Maximum Reverse Leakage Current		Typical Temperature coefficient @ IZTC=mVrc		I _{est} Current IZTC
		VZ Nom.(V)	VZ Min.(V)	VZ Max.(V)	IZT (mA)	ZZT@IZT (Ω)	ZZK@IZK (Ω)	IZK (mA)	IR@VR (uA)	VR (V)	Min	Max	
BZX84B2V4	2Z11	2.4	2.35	2.45	5	100	600	1.0	50	1.0	-3.5	0	5
BZX84B2V7	2Z12	2.7	2.65	2.75	5	100	600	1.0	20	1.0	-3.5	0	5
BZX84B3V0	2Z13	3.0	2.94	3.06	5	95	600	1.0	10	1.0	-3.5	0	5
BZX84BV3	2Z14	3.3	3.23	3.37	5	95	600	1.0	5	1.0	-3.5	0	5
BZX84B3V6	2Z15	3.6	3.53	3.67	5	90	600	1.0	5	1.0	-3.5	0	5
BZX84B3V9	2Z16	3.9	3.82	3.98	5	90	600	1.0	3	1.0	-3.5	0	5
BZX84B4V3	2Z17	4.3	4.21	4.39	5	90	600	1.0	3	1.0	-3.5	0	5
BZX84B4V7	2Z1	4.7	4.61	4.79	5	80	500	1.0	3	2.0	-3.5	0.2	5
BZX84B5V1	2Z2	5.1	5.00	5.20	5	60	480	1.0	2	2.0	-2.7	1.2	5
BZX84B5V6	2Z3	5.6	5.49	5.71	5	40	400	1.0	1	2.0	-2.0	2.5	5
BZX84B6V2	2Z4	6.2	6.08	6.32	5	10	150	1.0	3	4.0	0.4	3.7	5
BZX84B6V8	2Z5	6.8	6.66	6.94	5	15	80	1.0	2	4.0	1.2	4.5	5
BZX84B7V5	2Z6	7.5	7.35	7.65	5	15	80	1.0	1	5.0	2.5	5.3	5
BZX84B8V2	2Z7	8.2	8.04	8.36	5	15	80	1.0	0.7	5.0	3.2	6.2	5
BZX84B9V1	2Z8	9.1	8.92	9.28	5	15	100	1.0	0.5	6.0	3.8	7.0	5
BZX84B10	2Z9	10	9.80	10.20	5	20	150	1.0	0.2	7.0	4.5	8.0	5
BZX84B11	2Y1	11	10.78	11.22	5	20	150	1.0	0.1	8.0	5.4	9.0	5
BZX84B12	2Y2	12	11.76	12.24	5	25	150	1.0	0.1	8.0	6.0	10.0	5
BZX84B13	2Y3	13	12.74	13.26	5	30	170	1.0	0.1	8.0	7.0	11.0	5
BZX84B15	2Y4	15	14.70	15.30	5	30	200	1.0	0.1	10.5	9.2	13.0	5
BZX84B16	2Y5	16	15.68	16.32	5	40	200	1.0	0.1	11.2	10.4	14.0	5
BZX84B18	2Y6	18	17.64	18.36	5	45	225	1.0	0.1	12.6	12.4	16.0	5
BZX84B20	2Y7	20	19.60	20.40	5	55	225	1.0	0.1	14.0	14.4	18.0	5
BZX84B22	2Y8	22	21.56	22.44	5	55	250	1.0	0.1	15.4	16.4	20.0	5
BZX84B24	2Y9	24	23.52	24.48	5	70	250	1.0	0.1	16.8	18.4	22.0	5
BZX84B27	2Y10	27	26.46	27.54	2	80	300	0.5	0.1	18.9	21.4	25.3	2
BZX84B30	2Y11	30	29.40	30.60	2	80	300	0.5	0.1	21.0	24.4	29.4	2
BZX84B33	2Y12	33	32.34	33.66	2	80	325	0.5	0.1	23.1	27.4	33.4	2
BZX84B36	2Y13	36	35.28	36.72	2	90	350	0.5	0.1	25.2	30.4	37.4	2
BZX84B39	2Y14	39	38.22	39.78	2	130	350	0.5	0.1	27.3	33.4	41.2	2
BZX84B43	2Y15	43	41.16	43.84	2	100	700	1.0	0.1	32.0	10.0	12.0	5
BZX84B47	2Y16	47	46.06	47.94	2	100	750	1.0	0.1	35.0	10.0	12.0	5
BZX84B51	2Y17	51	49.98	52.02	2	100	750	1.0	0.1	38.0	10.0	12.0	5
BZX84B56	2Y18	56	54.88	57.12	2	135	700	1.0	0.1	42.0	10.0	12.0	5
BZX84B62	2Y19	62	60.76	63.24	2	200	1000	1.0	0.2	47.0	10.0	12.0	5
BZX84B68	2Y20	68	66.64	69.36	2	250	1000	1.0	0.2	52.0	10.0	12.0	5
BZX84B75	2Y21	75	73.5	76.5	2	300	1000	1.0	0.2	57.0	10.0	12.0	5

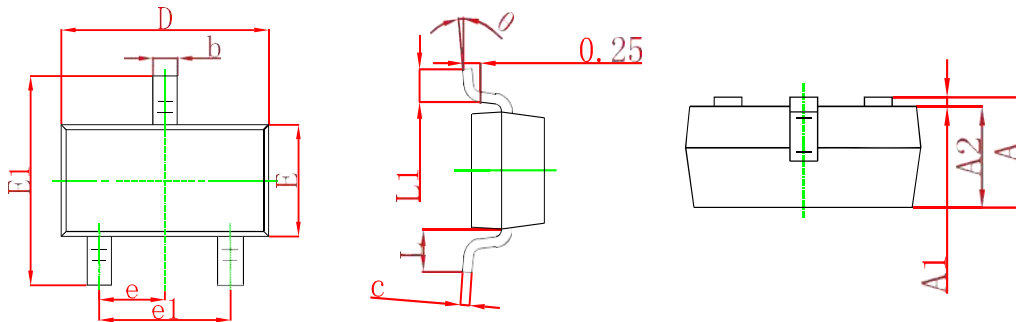
Notes:

1. The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C .
2. Short duration test pulse used to minimize self-heating effect
3. f=1KHZ

Typical Characteristics



Package Outlines (Dimensions in mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

*Important Usage Information and Disclaimer

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